

Rosin Cored Solder Wire (anti peel-off & Splattering Reduction)

Prevent flux peel-off and dramatically reduce splattering

GUMMIX Series (GUMMIX-19, GUMMIX-19CH, GUMMIX SB)

Ideal for precision work in which flux/solder ball splattering must be eliminated. Superb for flexible substrates and/or parts where flux residue may be peel-off by vibration. GUMMIX Series is ideal for a wide variety of applications.



[Application] ● No-clean process, prevention of flux/solder ball splattering, prevention of flux residue peel-off, non-contact heating (laser, xenon lamp and other products), motor, relay, optical pick-up, Speaker, CCD, contacts and mechanicals.

Preventing flux peel-off and reducing splattering

[Separation Test] Flux peel-off comparison

● Cross-cutting test (JIS K 5600-6)

Test Conditions

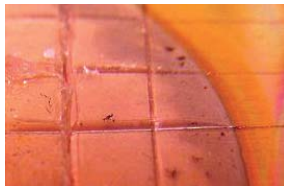
- Place flux sample (0.03g) on Cu substrate (30x30x0.5mm) and heat the substrate at 340°C for 3 sec.
- Preparing sample by six slashes in 2mm interval vertically and horizontally in the sample substrate.
- Tape to the substrate and examine the surface after removing the tape.

General Rosin-Cored Solder



Peel-off was observed across the sample substrate.

GUMMIX-19CH



Cut edge is smooth and peel-off was not observed

● Cu Substrate Bending Test (assuming flexible substrate use)

Test Conditions

- Bend the sample substrate used for cross-cutting test and observe flux residue.

General Rosin-Core Solder



Major peel-off was observed.

GUMMIX-19CH

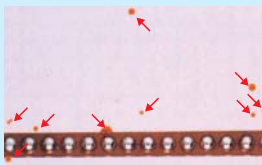


No peel-off was observed.

GUMMIX Series can minimize flux peel-off and ideal for use in flexible substrates.

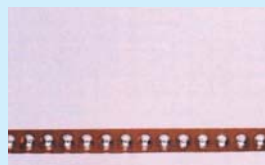
[Splash Test] Flux splattering comparison

Equivalent Competitive Product



Splattering was observed.

GUMMIX-19CH



No splattering was observed.

Examples of GUMMIX Series use <Major relay manufacturer>

Achieved Big cost reductions by eliminating cleaning process.

One of our customers manufacturing coil for automotive industries succeeded cost saving up to \$US1.3 million by eliminating cleaning process in addition to increasing productivity by introducing ALMIT GUMMIX solder to their productions. Another customer involved in relay assembly has also been able to achieve similar cost reductions using GUMMIX solder.

GUMMIX Series can minimize flux splattering, and will help to reduce time and cost.

*For further information, please contact our sales representatives at the addresses below.

Line-up of Rosin-Core Solder

GUMMIX-19CH LFM-48 3.5% 1.0 φ

Flux + Alloy + Flux Content + Wire Diameter

Rosin-Cored Solder Specifications

Flux	Alloy composition	Flux Content	Melting Temperature	Wire Diameter
GUMMIX Series	LFM-48 (Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3, 0.38, 0.5, 0.65, 0.8, 1.0, 1.2, 1.6

※ LFM-48 holds the sublicenses for JP PAT No. 3027441 and US PAT No. 5527628

※ Ask Almit sales representative for availability of the type and wire diameter in detail.